PATENT DOCKET NO. 420099-654 LLC P-2880/1D

> #2/17 12-2997

I hereby certify that this correspondence and any attachments are being deposited August 14, 1997, with the United States Postal Service as Express Mail in an envelope addressed to: Box New Application, Honorable Commissioner of Patents and Trademarks, Washington, D.C. 20231.

Express Mail No. EI143570081US

le A. Healion

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application Of:

MIKE LIANG

Serial Number:

Filed: Herewith

Entitled: FLIP CHIP BUMP DISTRIBUTION ON DIE

Examiner:

Box New Application Honorable Commissioner of Patents and Trademarks Washington, D.C. 20231

PRELIMINARY AMENDMENT

Sir:

Preliminary to the initial Office Action, please amend the above-captioned divisional application as set forth below.

